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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TC 1700

In re application of

Akihisa HONGO et al.

Serial No. 09/762,582

Filed April 12, 2001

: Confirmation No.

: Docket No. 2001\_0133A

: Group Art Unit 1741

: Examiner Brian Mutschler

SUBSTRATE PLATING  
METHOD AND APPARATUS

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

Sir:

In response to the Office Action of May 7, 2003, the period for response to which having been extended by three months to November 7, 2003, please amend the above-identified U.S. Patent Application as follows: